

ABSTRACT

Provided are an electroplating fixture, an electroplating apparatus, and an electroplating fixture detection method. The electroplating fixture comprises a clamping cylinder and a sealing ring, wherein an annular boss is arranged on the inner wall of the clamping cylinder, and the annular boss is used for supporting a wafer; the sealing ring wraps the annular boss and extends from the annular boss to the cylinder wall of the clamping cylinder; a gas channel is arranged in the cylinder wall of the clamping cylinder, and a gas channel opening is arranged at the position where the clamping cylinder is wrapped by the sealing ring. Whether the sealing ring is damaged can be detected by evacuating gas through the gas channel. The electroplating fixture can realize reliable electroplating of the wafer.